

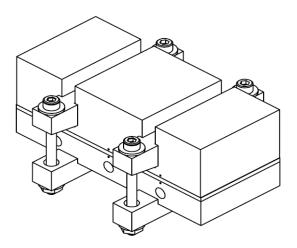
# **Tflex SF600DF Thermal Reliability Report**

## Summary

The Laird Technologies gap filler reliability test procedure has been designed to characterize the long-term performance of a gap pad while being subjected to isothermal conditions, repeated extremes in temperature, and moderate heat - high humidity environments. Specimens are placed within application-related fixtures under set conditions and at regular intervals the thermal properties of the specimens are measured.

# **Fixture Setup**

The test fixture is rectangular with dimensions of 2" x 5" (surface area of 10 in<sup>2</sup>). It consists of an aluminum heater plate and an extruded aluminum heat sink "cooler plate". The heater plate contains 3 holes for insertion of cartridge heaters. Both plates contain 3 sets of thermocouple holes drilled for measurement of the temperature very near the surfaces mated by the gap pad. Each test fixture accommodates 3 test positions. The heater and cooler plates are held together by metal straps which span the width of the plates (2 sets per test fixture) and are bolted to each other. Cartridge heaters are inserted into the heater plate holes. A specified power from a power supply is input to the heaters to obtain a constant 70<sup>o</sup>C across the heater plate. This will ensure a constant heat flow is maintained through the gap filler during data acquisition. A cooling fan is centered on top of the heat sink during testing to facilitate realistic air flow and cooling. Test values are measured in an ambient laboratory environment.



## Theory

Temperature difference between the surfaces of the heater and cooler plates are monitored throughout the testing. Thermal resistance ( $R_{th}$ ) is defined as the temperature difference ( $\Delta T$ ) between two surfaces for a given heat flow ( $\Delta P$ ). That is:  $R_{th} = \Delta T / \Delta P$ . In this testing, heat flow is controlled and constant, therefore,  $R_{th} \alpha \Delta T$ . This relationship indicates that a constant value of  $\Delta T$  throughout the test program requires  $R_{th}$  to also remain constant, indicating a highly reliable system and thus a gap pad that is not influenced by the test conditions.



# **Types of Reliability Testing**

#### **Thermal Shock**

In thermal shock testing, the test fixtures containing the specimens are transitioned between  $-40^{\circ}$ C and  $110^{\circ}$ C with a 1 hour hold to reach thermal equilibrium at each temperature extreme. The transfer time between the oven temperatures is quick, typically less than 20 seconds. 1000 cycles "Shocks" are performed on each fixture.

#### **Isothermal Bake**

In isothermal bake testing, fixtures are maintained at 120<sup>°</sup>C for 1000 hours.

#### HAST

In HAST testing, the fixtures are maintained in conditions of moderate temperature  $(85^{\circ}C)$  and high humidity (85%) for the duration of the test.

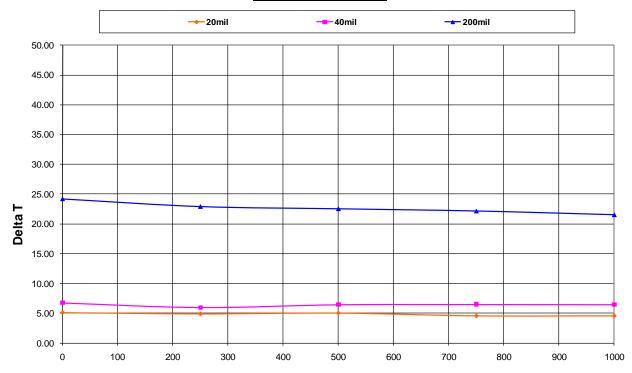
### Results

The thicknesses of Tflex SF600DF tested were 20mil (0.508mm), 40mil (1.016mm), and 200mil (5.08mm). Two fixtures for each thickness were assembled and tested for all three reliability testing types (3 test positions for each unit). The data reported is the average of each value for the two fixtures.

The change in temperature ( $\Delta T$ ) vs. time / # of cycles tested is reported below:



**Thermal Shock** 



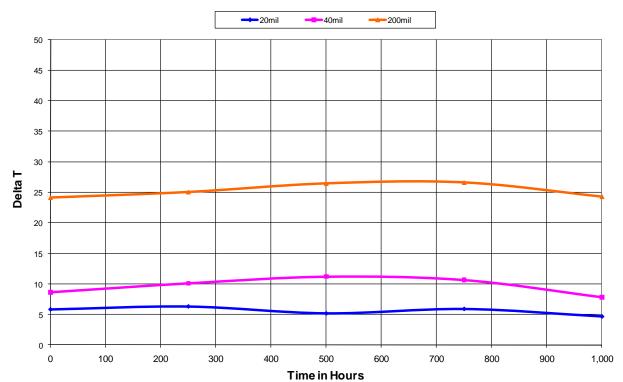
**Time in Hours** 

Material	Cycles	Avg ∆T
Tflex SF620DF	0	5.07
	250	4.86
	500	5.00
	750	4.52
	1000	4.53
Tflex SF640DF	0	6.76
	250	5.95
	500	6.45
	750	6.48
	1000	6.46
Tflex SF6200DF	0	24.18
	250	22.89
	500	22.52
	750	22.15
	1000	21.52



# Isothermal Bake

Tflex SF600DF Delta T over 1000 hours @ 120°C

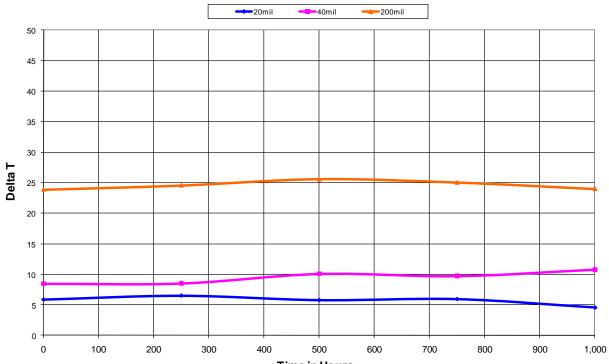


Material	Hours	Avg ∆T
Tflex SF620DF	0	5.82
	250	6.30
	500	5.18
	750	5.90
	1000	4.66
Tflex SF640DF	0	8.62
	250	10.11
	500	11.21
	750	10.65
	1000	7.79
Tflex SF6200DF	0	24.12
	250	25.03
	500	26.43
	750	26.58
	1000	24.28





#### Tflex SF600DF Delta T over 1000 hours @ 85°C/85% Humidity



**Time in Hours** 

Material	Hours	Avg ΔT
Tflex SF620DF	0	5.85
	250	6.50
	500	5.76
	750	5.93
	1000	4.52
Tflex SF640DF	0	8.46
	250	8.51
	500	10.08
	750	9.71
	1000	10.78
Tflex SF6200DF	0	23.87
	250	24.54
	500	25.55
	750	25.01
	1000	23.99



#### **Conclusion:**

The graphs and data show little or no increase in  $\Delta T$  for Tflex SF600DF over the duration of testing for HAST, bake and thermal shock conditions. Based upon this data, no thermal degradation was evidenced and therefore, it is shown that Tflex SF600DF will continue to perform as designed in applications under harsh environmental conditions simulated by this procedure.

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